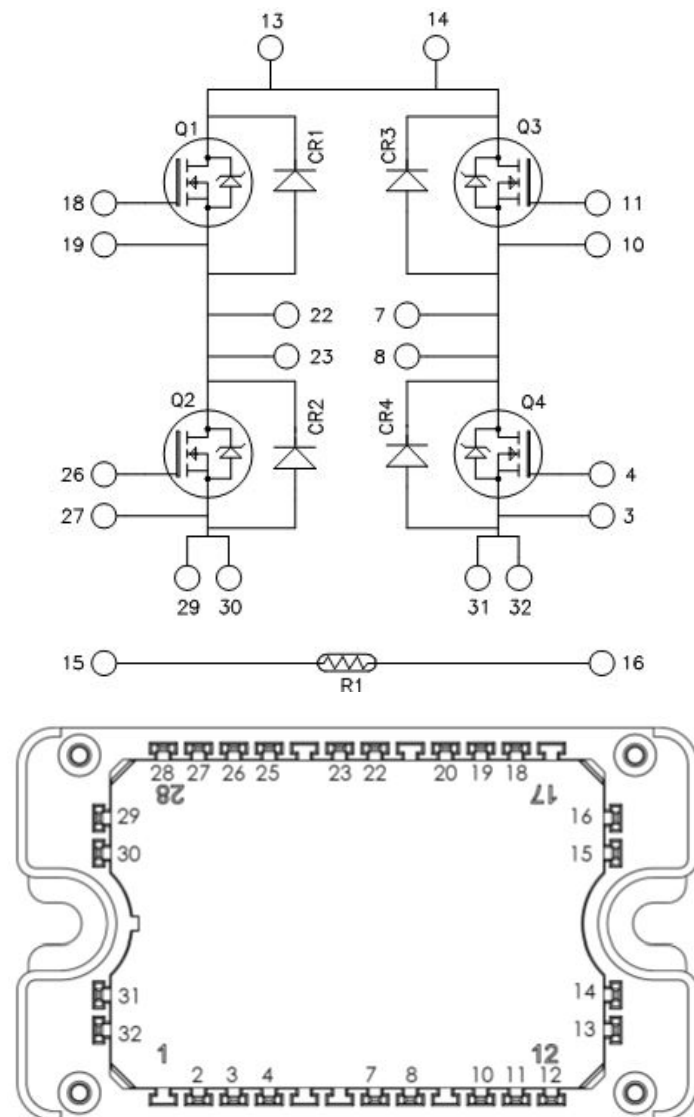


Full Bridge SiC MOSFET Power Module

Product Overview

The MSCSM170HM23CT3AG device is a full bridge 1700 V, 124 A silicon carbide (SiC) MOSFET power module.



Note: All multiple inputs and outputs, such as pins 13/14, 29/30, 22/23 and so on, must be shorted together.

All ratings at $T_J = 25\text{ }^\circ\text{C}$, unless otherwise specified.

Caution: These devices are sensitive to electrostatic discharge. Proper handling procedures must be followed.

Features

The following are key features of the MSCSM170HM23CT3AG device:

- SiC Power MOSFET
 - High speed switching
 - Low $R_{DS(on)}$
 - Ultra low loss
- SiC Schottky Diode
 - Zero reverse recovery
 - Zero forward recovery
 - Temperature independent switching behavior
 - Positive temperature coefficient on VF
- Very low stray inductance
- Kelvin source for easy drive
- Internal thermistor for temperature monitoring
- Aluminum nitride (AlN) substrate for improved thermal performance

Benefits

The following are the benefits of MSCSM170HM23CT3AG device:

- High efficiency converter
- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction-to-case thermal resistance
- Solderable terminals for power and signal for easy mounting of PCB
- Low profile
- RoHS compliant

Application

The MSCSM170HM23CT3AG device is designed for the following applications:

- Welding converters
- Switched mode power supplies
- Uninterruptible power supplies
- EV motor and traction drive

1. Electrical Specifications

This section provides the electrical specifications of the MSCSM170HM23CT3AG device.

1.1 SiC MOSFET Characteristics (Per SiC MOSFET)

The following table lists the absolute maximum ratings per SiC MOSFET of the MSCSM170HM23CT3AG device.

Table 1-1. Absolute Maximum Ratings

Symbol	Parameter	Maximum Ratings	Unit
V_{DSS}	Drain-Source voltage	1700	V
I_D	Continuous drain current	$T_C = 25\text{ }^\circ\text{C}$	124 ¹
		$T_C = 80\text{ }^\circ\text{C}$	98 ¹
I_{DM}	Pulsed drain current	240	
V_{GS}	Gate-Source voltage	-10/23	V
$R_{DS(on)}$	Drain-Source ON resistance	22.5	m Ω
P_D	Power dissipation	$T_C = 25\text{ }^\circ\text{C}$	602

Note:

1. Specification of the SiC MOSFET device but output current must be limited due to size of power connectors.

The following table lists the electrical characteristics per SiC MOSFET of the MSCSM170HM23CT3AG device.

Table 1-2. Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit	
I_{DSS}	Zero gate voltage drain current	$V_{GS} = 0\text{ V}; V_{DS} = 1700\text{ V}$	—	20	200	μA	
$R_{DS(on)}$	Drain-Source on resistance	$V_{GS} = 20\text{ V}$ $I_D = 60\text{ A}$	$T_J = 25\text{ }^\circ\text{C}$	—	17.5	22.5	m Ω
			$T_J = 175\text{ }^\circ\text{C}$	—	31	—	
$V_{GS(th)}$	Gate threshold voltage	$V_{GS} = V_{DS}; I_D = 5\text{ mA}$	1.8	3.2	—	V	
I_{GSS}	Gate-Source leakage current	$V_{GS} = 20\text{ V}; V_{DS} = 0\text{ V}$	—	—	200	nA	

The following table lists the dynamic characteristics per SiC MOSFET of the MSCSM170HM23CT3AG device.

Table 1-3. Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit	
C_{iss}	Input capacitance	$V_{GS} = 0\text{ V}$	—	6600	—	pF	
C_{oss}	Output capacitance	$V_{DS} = 1000\text{ V}$	—	300	—		
C_{rss}	Reverse transfer capacitance	$f = 1\text{ MHz}$	—	20	—		
Q_g	Total gate charge	$V_{GS} = -5\text{ V}/20\text{ V}$	—	356	—	nC	
Q_{gs}	Gate-Source charge	$V_{Bus} = 850\text{ V}$	—	98	—		
Q_{gd}	Gate-Drain charge	$I_D = 60\text{ A}$	—	54	—		
$T_{d(on)}$	Turn-on delay time	$T_J = 150\text{ °C}$	—	24	—	ns	
T_r	Rise time	$V_{GS} = -5\text{ V}/20\text{ V}$	—	17	—		
$T_{d(off)}$	Turn-off delay time	$V_{Bus} = 900\text{ V}$	—	35	—		
T_f	Fall time	$I_D = 100\text{ A}$ $R_{G(on)} = 2.4\ \Omega$ $R_{G(off)} = 1.4\ \Omega$	—	19	—		
E_{on}	Turn-on energy	$V_{GS} = -5\text{ V}/20\text{ V}$	$T_J = 150\text{ °C}$	—	2.2	—	mJ
E_{off}	Turn-off energy	$V_{Bus} = 900\text{ V}$ $I_D = 100\text{ A}$ $R_{G(on)} = 2.4\ \Omega$ $R_{G(off)} = 1.4\ \Omega$	$T_J = 150\text{ °C}$	—	0.33	—	
R_{Gint}	Internal gate resistance		—	2.93	—	Ω	
R_{thJC}	Junction-to-case thermal resistance		—	—	0.25	$^{\circ}\text{C}/\text{W}$	

The following table lists the body diode ratings and characteristics per SiC MOSFET of the MSCSM170HM23CT3AG device.

Table 1-4. Body Diode Ratings and Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
V_{SD}	Diode forward voltage	$V_{GS} = 0\text{ V}; I_{SD} = 60\text{ A}$	—	3.7	—	V
		$V_{GS} = -5\text{ V}; I_{SD} = 60\text{ A}$	—	3.9	—	
t_{rr}	Reverse recovery time	$I_{SD} = 60\text{ A}; V_{GS} = -5\text{ V}$	—	27	—	ns
Q_{rr}	Reverse recovery charge	$V_R = 900\text{ V}; di_F/dt = 2000\text{ A}/\mu\text{s}$	—	1300	—	nC
I_{rr}	Reverse recovery current		—	92	—	A

1.2 SiC Schottky Diode Ratings and Characteristics (Per SiC Diode)

The following table lists the SiC diode ratings and characteristics per SiC diode of MSCSM170HM23CT3AG device.

Table 1-5. SiC Schottky Diode Ratings and Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit	
V_{RRM}	Peak repetitive reverse voltage		—	—	1700	V	
I_{RRM}	Reverse leakage current	$V_R = 1700\text{ V}$	$T_J = 25\text{ °C}$	—	20	400	μA
			$T_J = 175\text{ °C}$	—	300	—	
I_F	DC forward current	—	$T_C = 125\text{ °C}$	—	60	—	A
V_F	Diode forward voltage	$I_F = 60\text{ A}$	$T_J = 25\text{ °C}$	—	1.5	1.8	V
			$T_J = 175\text{ °C}$	—	2.3	—	
Q_C	Total capacitive charge	$V_R = 900\text{ V}$	—	460	—	nC	
C	Total capacitance	$f = 1\text{ MHz}, V_R = 600\text{ V}$	—	334	—	pF	
		$f = 1\text{ MHz}, V_R = 900\text{ V}$	—	276	—		
R_{thJC}	Junction-to-case thermal resistance		—	—	0.276	$^{\circ}\text{C/W}$	

1.3 Thermal and Package Characteristics

The following table lists the thermal and package characteristics of the MSCSM170HM23CT3AG device.

Table 1-6. Thermal and Package Characteristics

Symbol	Characteristics	Min	Max	Unit		
V_{ISOL}	RMS isolation voltage, any terminal to case $t = 1\text{ min}$, 50 Hz/60 Hz	4000	—	V		
T_J	Operating junction temperature range	−40	175	$^{\circ}\text{C}$		
T_{JOP}	Recommended junction temperature under switching conditions	−40	$T_{Jmax} - 25$			
T_{STG}	Storage temperature range	−40	125			
T_C	Operating case temperature	−40	125			
Torque	Mounting torque	To heatsink	M4		2	3
Wt	Package weight	—	110	g		

MSCSM170HM23CT3AG

Electrical Specifications

The following table lists the temperature sensor NTC of the MSCSM170HM23CT3AG device.

Table 1-7. Temperature Sensor NTC

Symbol	Characteristic	Min	Typ	Max	Unit
R ₂₅	Resistance at 25 °C	—	50	—	kΩ
ΔR ₂₅ /R ₂₅	—	—	5	—	%
B _{25/85}	T ₂₅ = 298.15 K	—	3952	—	K
ΔB/B	—	T _C = 100 °C	4	—	%

$$R_T = \frac{R_{25}}{\exp\left[B_{25/85}\left(\frac{1}{T_{25}} - \frac{1}{T}\right)\right]}$$

T: Thermistor temperature
R_T: Thermistor value at T

Note: See [APT0406—Using NTC Temperature Sensor Integrated into Power Module](#) for more information.

1.4 Typical SiC MOSFET Performance Curve

This section shows the typical SiC MOSFET performance curves of the MSCSM170HM23CT3AG device.

Figure 1-1. Maximum Thermal Impedance

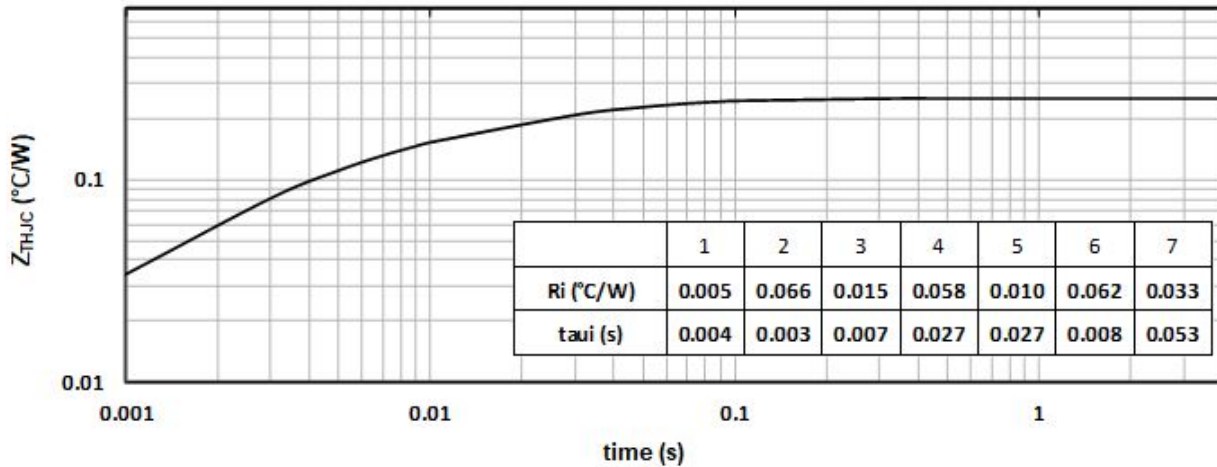


Figure 1-2. Output Characteristics, $T_J = 25^\circ\text{C}$

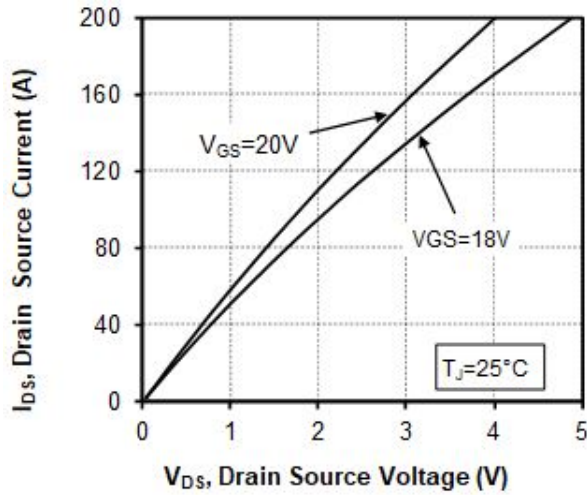


Figure 1-3. Output Characteristics, $T_J = 175^\circ\text{C}$

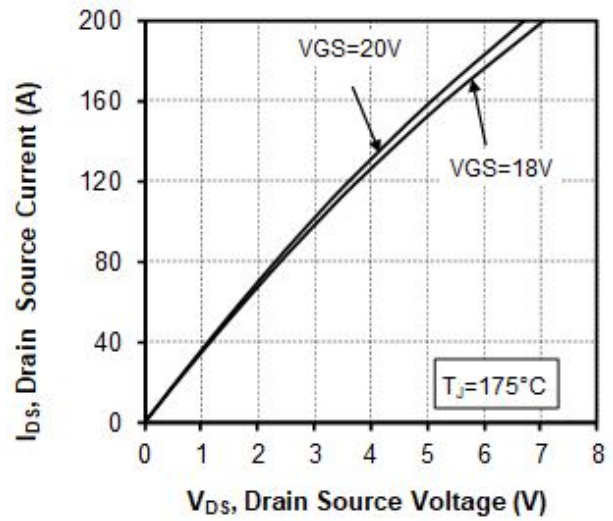


Figure 1-4. Normalized $R_{DS(on)}$ vs. Temperature

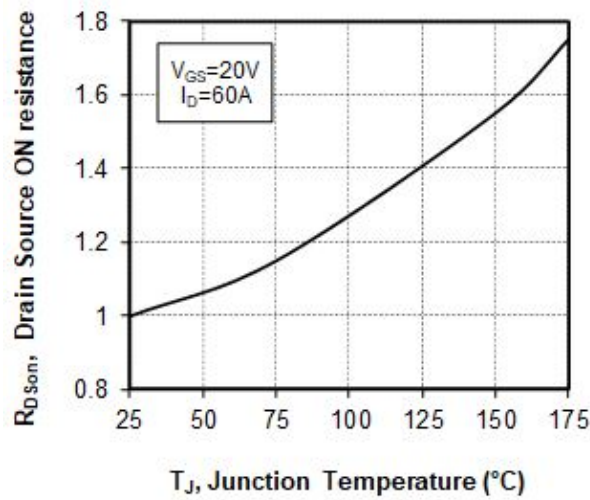


Figure 1-5. Transfer Characteristics

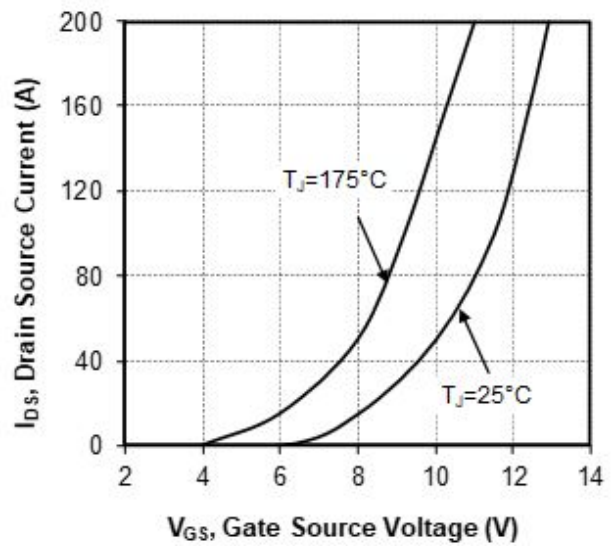


Figure 1-6. Switching Energy vs. Rg

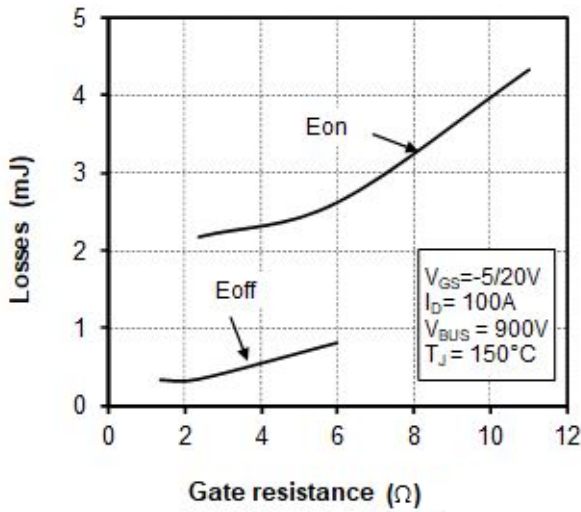


Figure 1-7. Switching Energy vs. Current

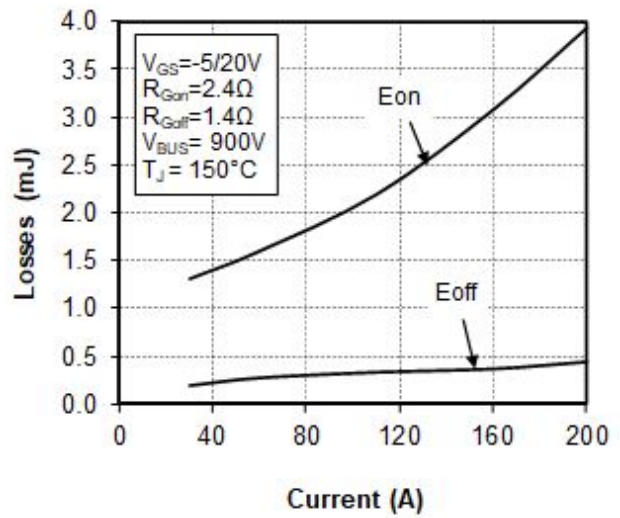


Figure 1-8. Capacitance vs. Drain Source Voltage

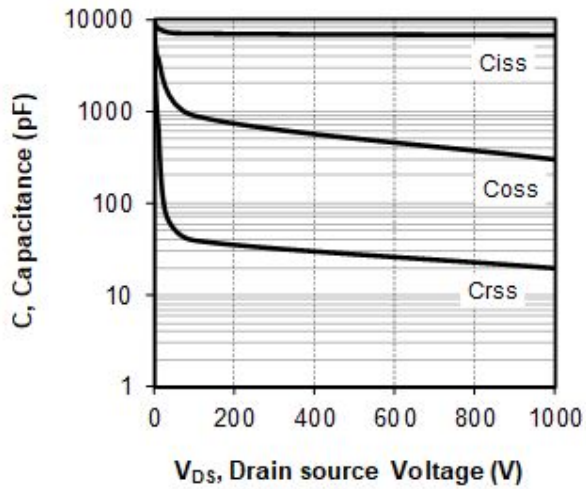


Figure 1-9. Gate Charge vs. Gate Source Voltage

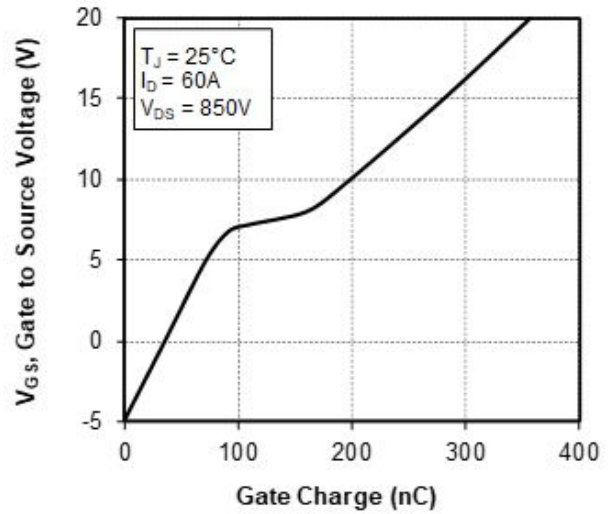


Figure 1-10. Body Diode Characteristics, $T_J = 25^\circ\text{C}$

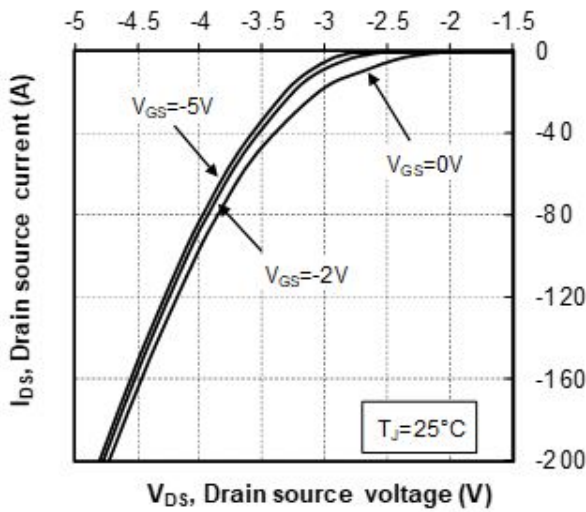


Figure 1-11. 3rd Quadrant Characteristics, $T_J = 25^\circ\text{C}$

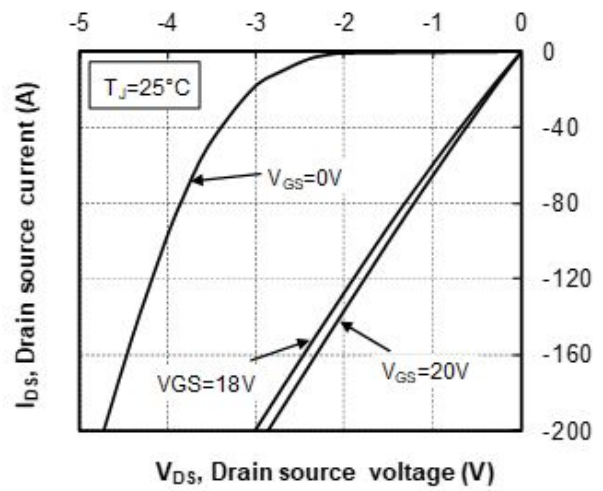


Figure 1-12. Body Diode Characteristics, $T_J = 175^\circ\text{C}$

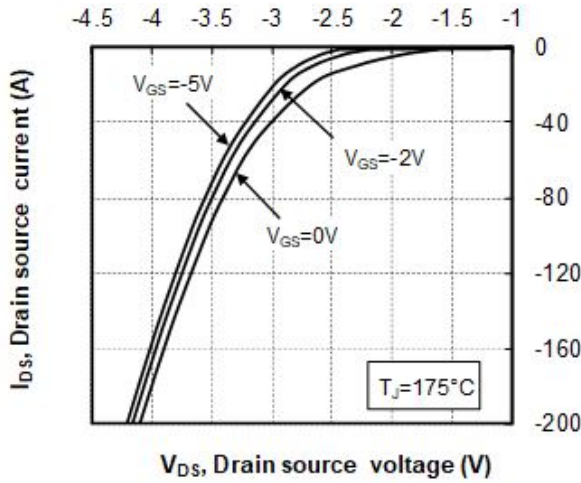


Figure 1-13. 3rd Quadrant Characteristics, $T_J = 175^\circ\text{C}$

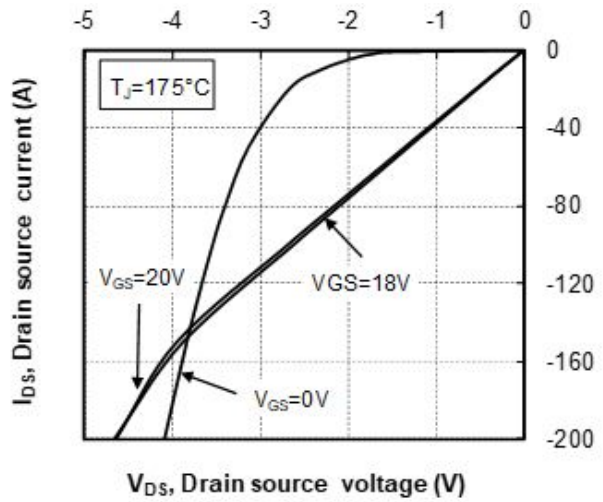
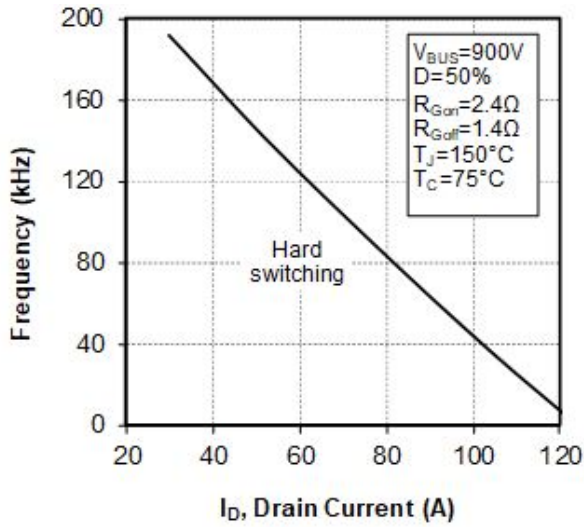


Figure 1-14. Operating Frequency vs Drain Current



1.5 Typical SiC Diode Performance Curves

This section shows the typical SiC diode performance curves of the MSCSM170HM23CT3AG device.

Figure 1-15. Maximum Thermal Impedance

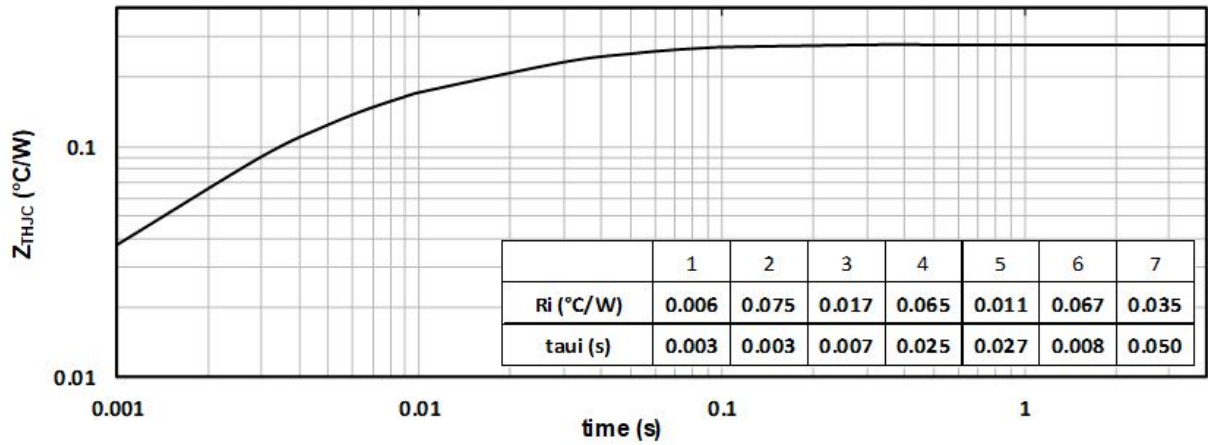


Figure 1-16. Forward Characteristics

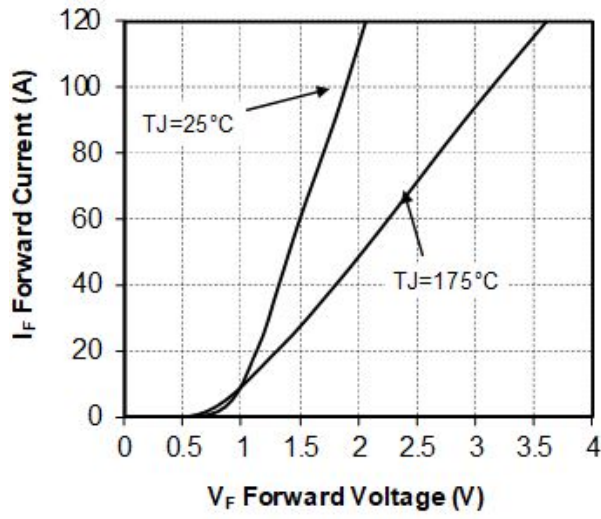
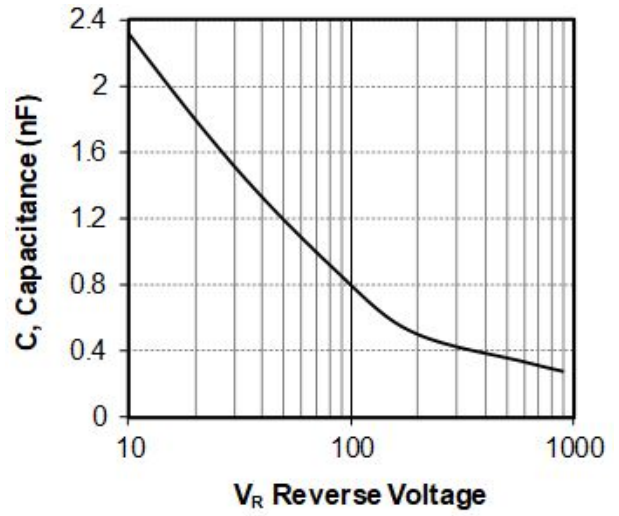


Figure 1-17. Capacitance vs. Reverse Voltage



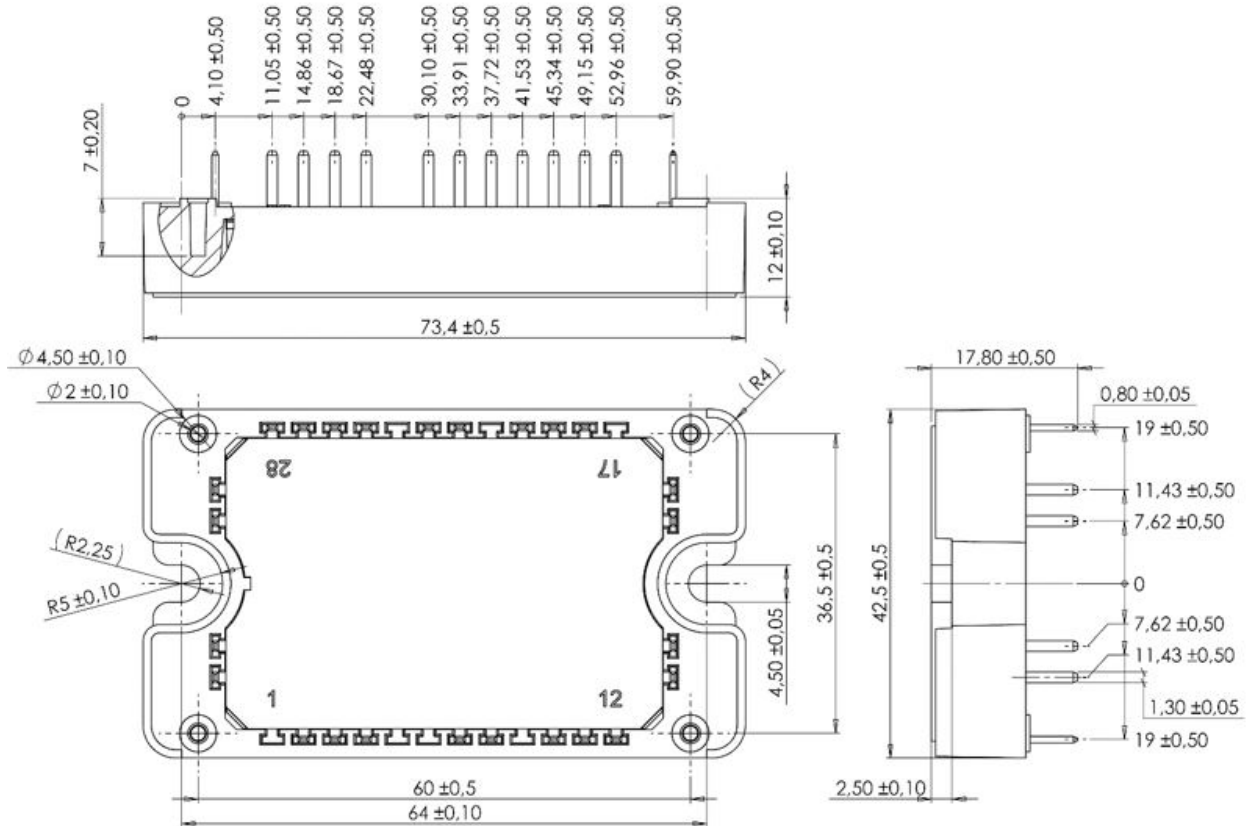
2. Package Specifications

The following section shows the package specification of the MSCSM170HM23CT3AG device.

2.1 Package Outline

The following figure shows the package outline drawing of the MSCSM170HM23CT3AG device. The dimensions in the following figure are in millimeters.

Figure 2-1. Package Outline Drawing



Note: See [AN3500A—Mounting Instructions for SP1F and SP3F Power Modules](#) for more information.

3. Revision History

Revision	Date	Description
A	04/2021	This is the first publication of this document.

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